

# Global G1 – Embedded form factor

MFF2, DFN8

## Product overview

A secure, device-agnostic IoT SIM card for global deployments built for M2M data, with easy activation, transparent pricing, and developer-friendly tools. Hologram's Hyper SIMs are eUICC compliant and the Hyper platform remotely updates coverage over-the-air by adding or removing profiles, without requiring you to swap the SIM in your device.

## Part numbers

G1-DFN8  
G1-DFN8-250  
G1-DFN8-2500

## Past part numbers

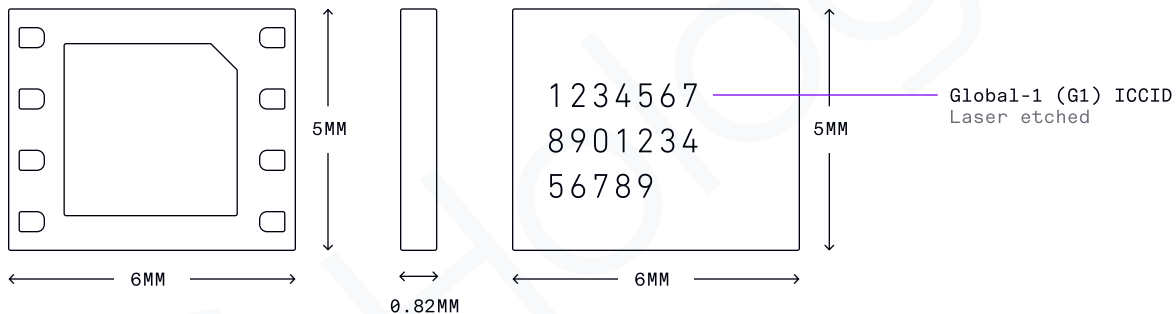
GL1-MFF2  
GL1-MFF2-250  
GL1-MFF2-2500  
SIM-E-MFF2-GL  
SIM-E-MFF2-GL-250  
SIM-E-MFF2-GL-2500

## Network availability

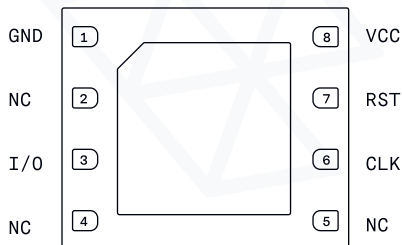
Works globally with Hologram's 2G through 4G (LTE) network including LTE-M and NB-IoT where coverage is available. More information: <https://www.hologram.io/pricing/coverage>

## Mechanical specifications

### Bottom view



### Top view



### Pin definitions

1	GND	Ground
2	NC	No Connect
3	I/O	Input/Output
4	NC	No Connect
5	NC	No Connect
6	CLK	Clock
7	RST	Reset
8	VCC	Input Voltage

### Size

MFF2 (DFN8)	Embedded SIM	6 × 5 × 0.82 mm
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## Hardware features

### Chip type

Supplier	Samsung
Chip Code	S3FW9FG

### Electrical

Operating Voltage	1.6V, 3V, and 5V
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### Hardware characteristics

Grade	Standard
Operational Temperature	-25°C to +85°C
Data Retention	25 years @ 25°C
Write Endurance	>500K read/write cycles @ 25°C (OS enhanced)
Memory (NVM)	340 KB
Memory (SRAM)	10 KB

### AC electrical parameters standards

ETSI 3GPP TS 102 221 Class A, B, C – UICC Terminal Interface Physical & Logical Characteristics  
 ETSI TS 102 671 v9.1.0 – M2M Physical and Logical Characteristics  
 ISO/IEC 7816-3 standard for Cards with Contacts – Electrical interface and transmission protocols

## Compliance

Chip	 Common Criteria	EAL: PP-0084/35
OS		SGP.11 RSP v3.1; SGP.14 eUICC PKI v1.1; SGP.02 v3.2 ; SGP.05 eUICC PP-0089
		eUICC Profile Package Interoperable Format Technical Specification v2.1
		Card Specification Version 2.1.1
Software		Java Card 3 Platform, Classic Edition version 3.0.4
		Release 8
Remote SIM provisioning		SGP.01 RSP v1.1 ; SGP.11 RSP v3.1 & 3.2; SGP.14 eUICC PKI v1.1 ; SAS-SM
Supplier's Declaration of Conformity		<p>Manufactured according to the following standards:</p> <ul style="list-style-type: none"> <li>• RoHS Directive 2011/65/EU</li> <li>• Reach certification</li> <li>• GSMA SAS-UP</li> <li>• ISO 9001:2015</li> <li>• ISO 27001</li> <li>• ISO 18001</li> <li>• ISO 17025</li> </ul>